

**Assembly Transfer of Select BGA Products  
to ASECL Taiwan**

**Qualification Plan Summary for  
23x23 BGA at ASECL Taiwan**

QUALIFICATION PLAN			
TEST	SPECIFICATION	SAMPLE SIZE	EXPECTED COMPLETION DATE
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 32	Sept 2021
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	Sept 2021
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	1 x 32	Pass
Unbiased Highly Accelerated Stress Test (UHAST)*	JEDEC <i>JESD22-A102</i>	3 x 32	Sept 2021

\* Preconditioned per JEDEC/IPC J-STD-020.